

Features

- · Trench LV MOSFET Technology
- ESD HBM Class 2
- · Operated at Low Logic Level Gate Drive
- · Moisture Sensitivity Level 3
- Halogen Free. "Green" Device (Note1)
- Epoxy Meets UL 94 V-0 Flammability Rating
- Lead Free Finish/RoHS Compliant ("P" Suffix Designates RoHS Compliant. See Ordering Information)

Maximum Ratings

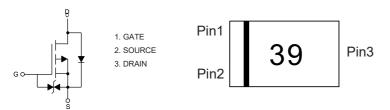
- Operating Junction Temperature Range: -55°C to +150°C
- Storage Temperature Range: -55°C to +150°C
- Thermal Resistance: 381°C/W Junction to Ambient^(Note2)

Parameter		Symbol	Rating	Unit	
Drain-Source Voltage	V _{DS}	-20	V		
Gate-Source Volltage		V_{GS}	±12	V	
Continuous Drain Current	T _A =25°C		-0.65	A	
	T _A =100°C	l _D	-0.41		
Pulsed Drain Current ^(Note3)		I _{DM}	-2.6	Α	
Total Power Dissipation ^(Note4)		P _D	0.33	W	

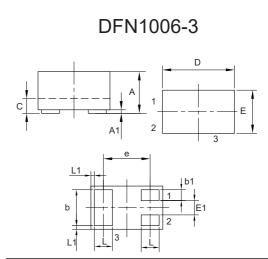
Note:

- 1. Halogen free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 2. The value of $R_{\theta JA}$ is measured with the device mounted on 1in^2 FR-4 board with 2oz. Copper, in a still air environment with T_A =25°C.
- 3. Repetitive rating; pulse width limited by max. junction temperature.
- 4. P_D is based on max. junction temperature, using junction-ambient thermal resistance.

Internal Structure and Marking Code

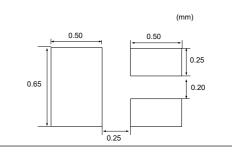


P-Channel MOSFET



DIMENSIONS					
DIM	INCHES		MM		NOTE
DIIVI	MIN	MAX	MIN	MAX	NOTE
Α	0.017	0.022	0.42	0.55	
A1	0.000	0.002	0.00	0.05	
b	0.018	0.022	0.45	0.55	
b1	0.004	0.008	0.10	0.20	
С	0.005	0.007	0.12	0.18	
D	0.037	0.041	0.95	1.05	
Е	0.022	0.026	0.55	0.65	
E1	0.006	0.010	0.15	0.25	
е	0.026		0.65		TYP.
L	0.008	0.012	0.20	0.30	
L1	0.0002		0.05		TYP.

Suggested Solder Pad Layout





ELECTRICAL CHARACTERISTICS (Ta=25°C unless otherwise specified)

Parameter	Symbol	Test conditions	Min	Тур	Max	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} =0V, I _D =-250μA	-20			V
Gate-Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =-250μA	-0.35	-0.62	-1.2	V
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±10V, V _{DS} =0V			±10	μA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =-20V, V _{GS} =0V			-1	μA
Drain-Source On-Resistance		V _{GS} =-4.5V, I _D =-500mA	0.6 0.85		0.85	Ω
	R _{DS(on)}	V _{GS} =-2.5V, I _D =-300mA		0.86	1.2	
		V _{GS} =-1.8V, I _D =-200mA		1.35	2	
Forward Transconductance	g _{FS}	V _{DS} =-5V, I _D =-600mA		1		S
Gate Resistance	R _g	f=1 MHz, Open drain		31		Ω
Diode Characteristics			,			
Continuous Body Diode Current	Is				-0.65	Α
Diode Forward Voltage	V _{SD}	V _{GS} =0V, I _S =-650mA			-1.2	V
Reverse Recovery Time	t _{rr}	I _F =-0.3A, dI _F /dt=100A/μs		8.6		ns
Reverse Recovery Charge	Q _{rr}	1 _F =-0.3A, α1 _F /α1=100A/μS		2.5		nC
Dynamic Characteristics	-					
Input Capacitance	C _{iss}			36		
Output Capacitance	C _{oss}	V _{DS} =-16V,V _{GS} =0V,f=1MHz		11		pF
Reverse Transfer Capacitance	C _{rss}			5.7		
Total Gate Charge	Q _g			1.24		
Gate-Source Charge	Q _{gs}	V _{DS} =-10V,V _{GS} =-4.5V,I _D =-0.3A		0.28		nC
Gate-Drain Charge	Q_{gd}			0.23		
Turn-On Delay Time	t _{d(on)}			4.2		
Turn-On Rise Time	t _r	V _{DD} =-10V,V _{GS} =-4.5V,		4.5		
Turn-Off Delay Time	t _{d(off)}	$R_G=2.5\Omega$, $I_D=-0.3A$		8.3		ns
Turn-Off Fall Time	t _f			4.4		

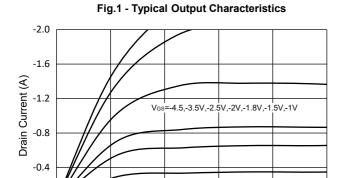


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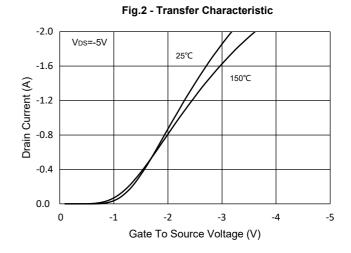
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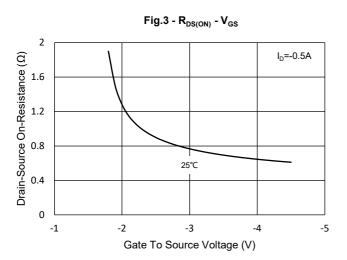
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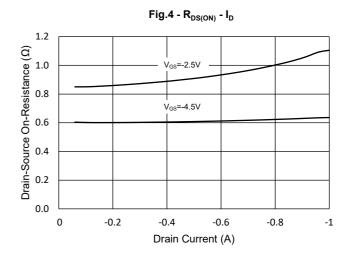
Curve Characteristics

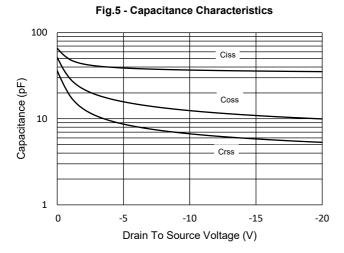


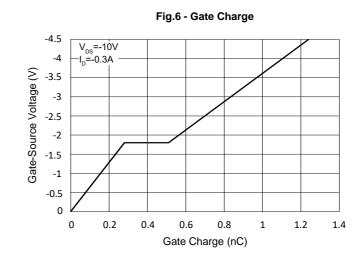
Drain To Source Voltage (V)





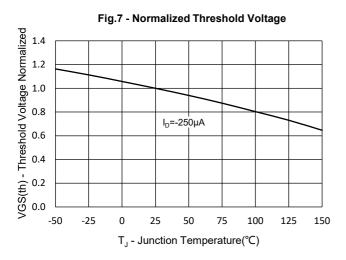


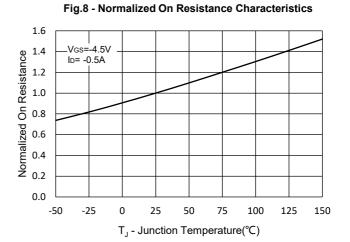


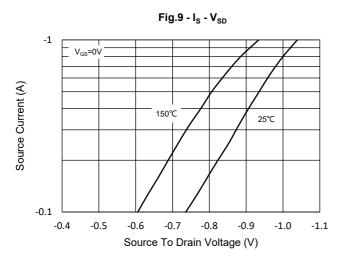


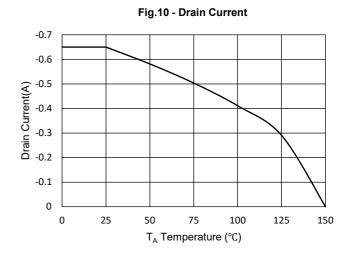


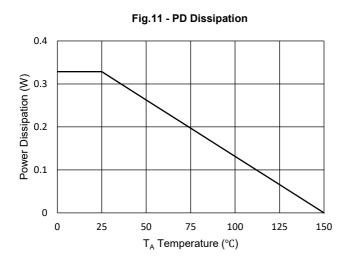
Curve Characteristics





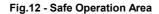








Curve Characteristics



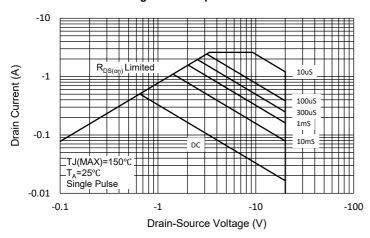
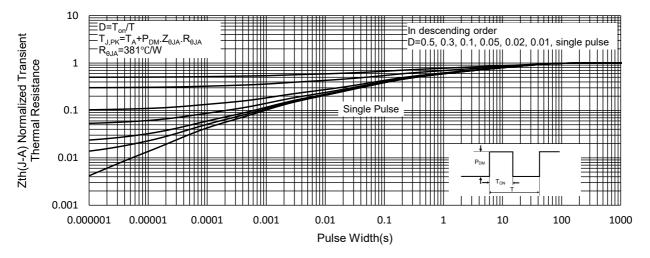


Fig.13 - Normalized Transient Thermal Impedance





Ordering Information

Device	Packing	
Part Number-TP	Tape&Reel:10Kpcs/Reel	
Part Number-TPQ3	Tape&Reel:10Kpcs/Reel	

For packaging details, go to our website at https://www.mccsemi.com/pdf/productpackaging/DFN1006-3%20Package.pdf

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